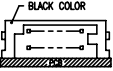
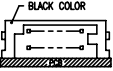
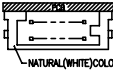
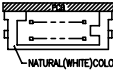


PRODUCT NO.

94898

PRODUCT NO.	STAND OFF	SOLDER TAIL	DIM "P" (mm)	DIM "Q" (mm)	FOR LOWER DECK OR UPPER DECK	③ HOLD DOWN	SHEET NO.	MOUNTING STYLE TO PCB
94898-XXXX	DIM "M" (mm)							
000	0	R/A	2.8	--	LOWER	NONE	NO.2	TOP MOUNT 94898-0XXX 
000LF	0	R/A	2.8	--	LOWER	NONE		
000MLF	0	R/A	2.8	--	LOWER	NONE		
000H	0	R/A	2.8	--	LOWER	YES		
000HLF	0	R/A	2.8	--	LOWER	YES		
001	0	SMT STAGGERED	--	--	LOWER	NONE		
001LF	0	SMT STAGGERED	--	--	LOWER	NONE		
001H	0	SMT STAGGERED	--	--	LOWER	YES		
001HLF	0	SMT STAGGERED	--	--	LOWER	YES		
002	0	SMT IN LINE	--	--	LOWER	NONE		
002LF	0	SMT IN LINE	--	--	LOWER	NONE	NO.3	BLACK COLOR 
002H	0	SMT IN LINE	--	--	LOWER	YES		
002HLF	0	SMT IN LINE	--	--	LOWER	YES		
010	4	R/A	2.8	--	LOWER	NONE		
010LF	4	R/A	2.8	--	LOWER	NONE		
020	5	R/A	2.8	--	LOWER	NONE		
020LF	5	R/A	2.8	--	LOWER	NONE		
020MLF	5	R/A	2.8	--	LOWER	NONE		
021MLF	5	R/A	2.8	--	LOWER	NONE		
040	2	R/A	2.5	--	LOWER	NONE		
040MLF	2	R/A	2.5	--	LOWER	NONE	NO.4	
040LF	2	R/A	2.5	--	LOWER	NONE		
005	FDR 0	R/A	2.8	8.6	UPPER	NONE		
005LF	FDR 0	R/A	2.8	8.6	UPPER	NONE		
045	FDR 2	R/A	2.5	10.3	UPPER	NONE		
045MLF	FDR 2	R/A	2.5	10.3	UPPER	NONE		
045LF	FDR 2	R/A	2.5	10.3	UPPER	NONE		
500	0	R/A	2.8	--	LOWER	NONE		
500LF	0	R/A	2.8	--	LOWER	NONE		
500H	0	R/A	2.8	--	LOWER	YES		
500HLF	0	R/A	2.8	--	LOWER	YES	NO.5	BOTTOM MOUNT 94898-5XXX 
501	0	SMT STAGGERED	--	--	LOWER	NONE		
501LF	0	SMT STAGGERED	--	--	LOWER	NONE		
501H	0	SMT STAGGERED	--	--	LOWER	YES		
501HLF	0	SMT STAGGERED	--	--	LOWER	YES		
502	0	SMT IN LINE	--	--	LOWER	NONE		
502J	0	SMT IN LINE	--	--	LOWER	NONE		
502LF	0	SMT IN LINE	--	--	LOWER	NONE		
502H	0	SMT IN LINE	--	--	LOWER	YES		
502HLF	0	SMT IN LINE	--	--	LOWER	YES		
510	4	R/A	2.8	--	LOWER	NONE	NO.6	NATURAL (WHITE) COLOR 
510LF	4	R/A	2.8	--	LOWER	NONE		
520	5	R/A	2.8	--	LOWER	NONE		
520LF	5	R/A	2.8	--	LOWER	NONE		
530	2	R/A	1.48	--	LOWER	NONE		
530LF	2	R/A	1.48	--	LOWER	NONE		
540	2	R/A	2.5	--	LOWER	NONE		
540LF	2	R/A	2.5	--	LOWER	NONE		
505	FDR 0	R/A	2.8	8.6	UPPER	NONE		
505LF	FDR 0	R/A	2.8	8.6	UPPER	NONE	NO.7	
535	FDR 2	R/A	1.48	9.28	UPPER	NONE		
535LF	FDR 2	R/A	1.48	9.28	UPPER	NONE		
545	FDR 2	R/A	2.5	10.3	UPPER	NONE		
545LF	FDR 2	R/A	2.5	10.3	UPPER	NONE		

NOTES

1. PRODUCT SPEC:110-263

94898-X X X X X

OPTIONAL LEED FREE

NONE : N □

LF : YES

OPTIONAL HOLD DOWN

NONE : N □

H : YES (SEE FIGURE OF -xxxH)

LOW COST VERSION

NONE : N □

M : YES (DETAIL AS COMPONENT)

SOLDER TAIL

0 : R/A (FOR LOWER & SINGLE)

1 : SMT STAGGERED (FOR LOWER ONLY)

2 : SMT IN LINE (FOR LOWER ONLY)

5 : R/A (FOR UPPER ONLY)

STAND OFF

0 : 0mm

1 : 4mm

2 : 5mm

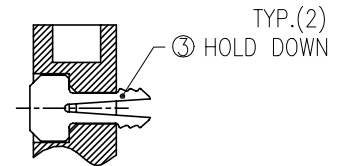
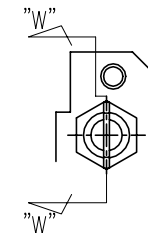
3 : 2mm (SPECIAL TAIL LENGTH)

4 : 2mm

MOUNTING STYLE

0 : TOP MOUNTING

5 : BOTTOM MOUNTING



SECTION "W"-"W"

94898-xxxH
(OPTIONAL HOLD DOWN)

mat'l. code					surface		tolerance		projection		product family					
					ISO 1302		ISO 406 ISO 1101				PCMCIA					
ltr	ecn no	dr	date		tolerances unless otherwise specified					title						
J	N06-0065	M.Z	04/02/06		angles linear		0.X±0.3				68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE					
K	N07-0219	M.Z	12/07/07				0.XX±0.13									
L	N08-0041	M.Z	03/10/08		±2°		0.XXX±0.05		scale 1:1							
M	N08-0219	M.Z	10/10/08		dr	M.Hasegawa		2/24/05				dwg no		sheet 1 of 7		size
N	N09-0045	SH	05/25/09		engr	M.Hasegawa		2/24/05				94898				A4
P	ELX-N-007954	ZK	11/01/11		chr											
R	ELX-N-011436	ZK	04/23/12		appd							type		CUSTOMER		Drawing
sheet revision		R	R	R	R	R	R	R								
index sheet		1	2	3	4	5	6	7								

PRODUCT NO.

94898-000

94898-000LF

94898-000H

94898-000HLF

94898-000MLF

94898-001

94898-001LF

94898-001H

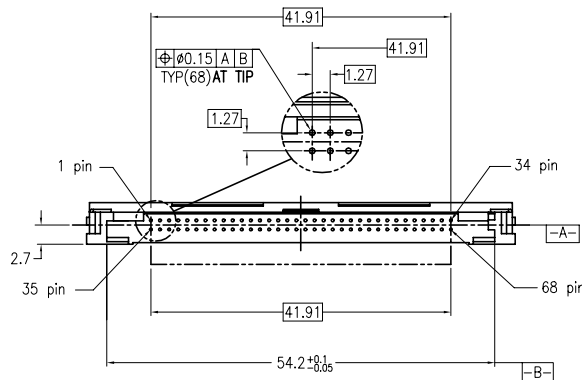
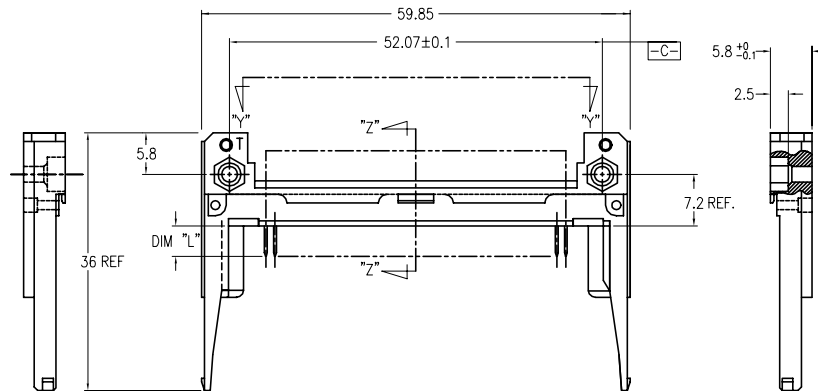
94898-001HLF

94898-002

94898-002LF

94898-002H

94898-002HLF



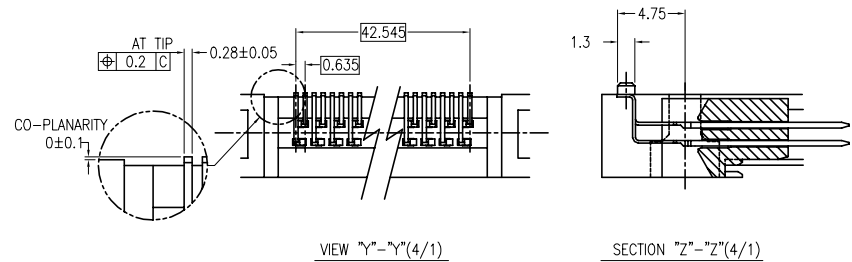
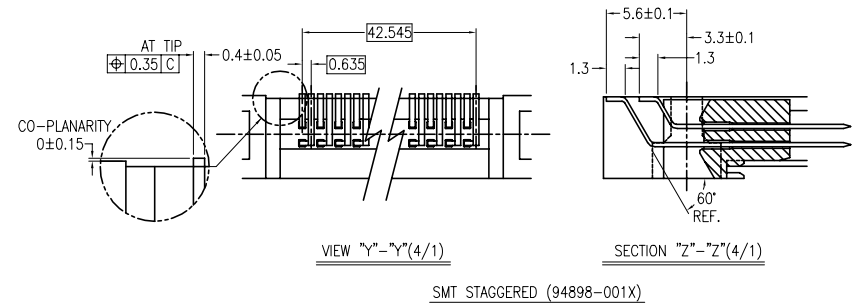
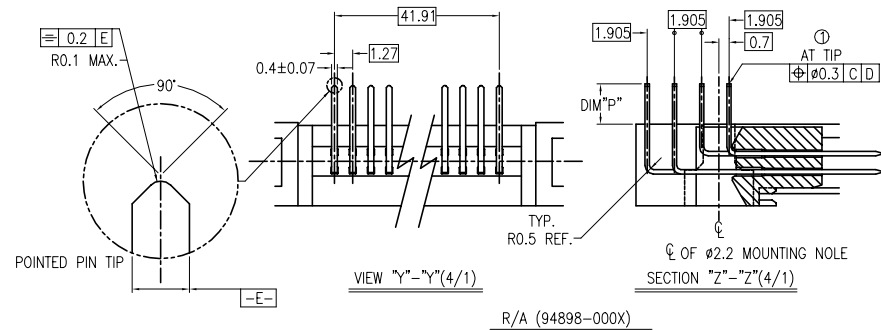
NOTES

- TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
- SEE TA-946 FOR PCB LAYOUT.
- MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
- FINISH
PIN
UNDER PLATING : 0.5µm MIN. Ni.
CONTACT AREA : 0.076 µm MIN. GOLD

SOLDER AREA : 2.5µm MIN. Sn-Pb.
OR 2.5µm MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5µm MIN. PURE Sn.
- RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
- SEQUENCE PIN ASSIGNMENT

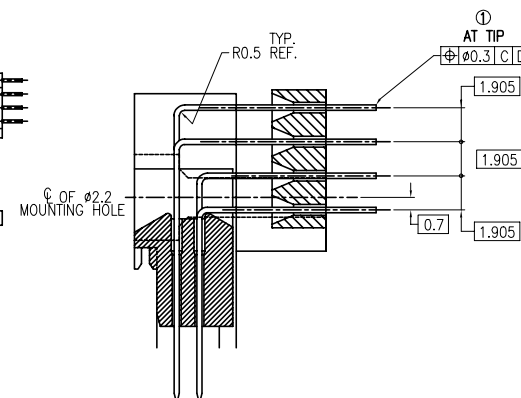
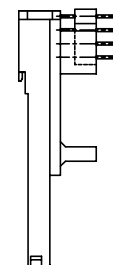
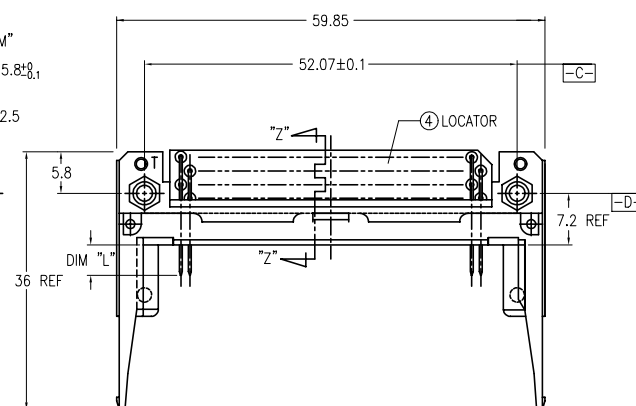
PIN No.	DIM "I"		
	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36.67	1.17±0.14	35.51±0.08

- GENERAL TOLERANCE : ±0.3
- SEE SHEET 1 REGARDING COMPONENTS.
- IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
- IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION

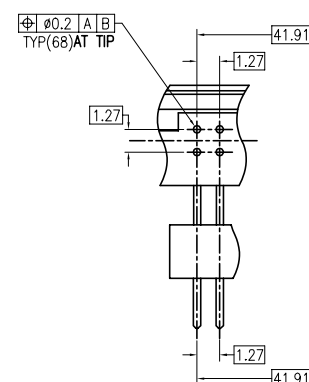
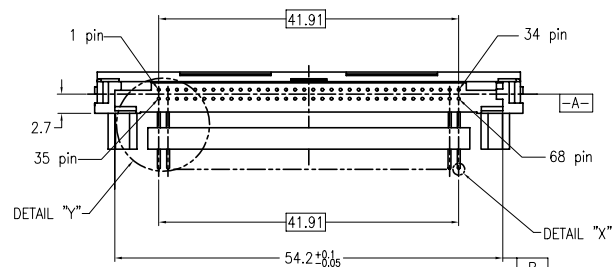


mat'l. code		surface		tolerance		projection		product family	
ISO 1302		ISO 406		ISO 1101		ISO 1101		PCMCIA	
ltr ecn nodr date		tolerances unless otherwise specified		title		title		title	
R		angles		linear		MM		68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE	
		±2°		0.X±0.3		scale 1:1		dwg no	
		dr M.Hasegawa 2/24/05		0.XX±0.13		sheet 2 of 7		size	
		engr M.Hasegawa 2/24/05		0.XXX±0.05		FCI		94898	
		chr				type CUSTOMER		Drawing	
		appd							
sheet index		revision sheet							

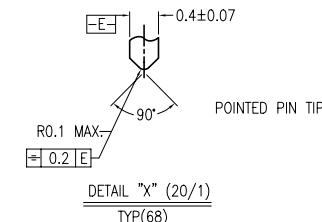
94898-040LF/040MLF



SECTION "Z"-"Z" (5/1)



DETAIL "Y" (5/1)



DETAIL "X" (20/1)
TYP(68)

- ① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
- ③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
- ④ FINISH
PIN
UNDER PLATING : 0.5 μ m MIN. Ni.
CONTACT AREA : 0.076 μ m MIN. GOLD

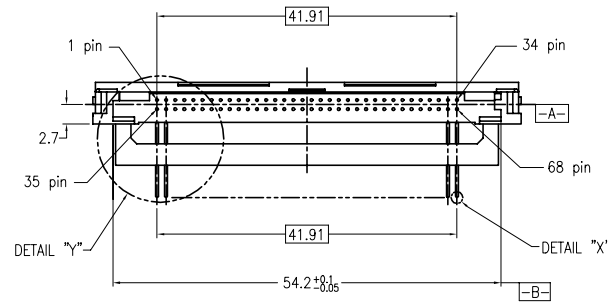
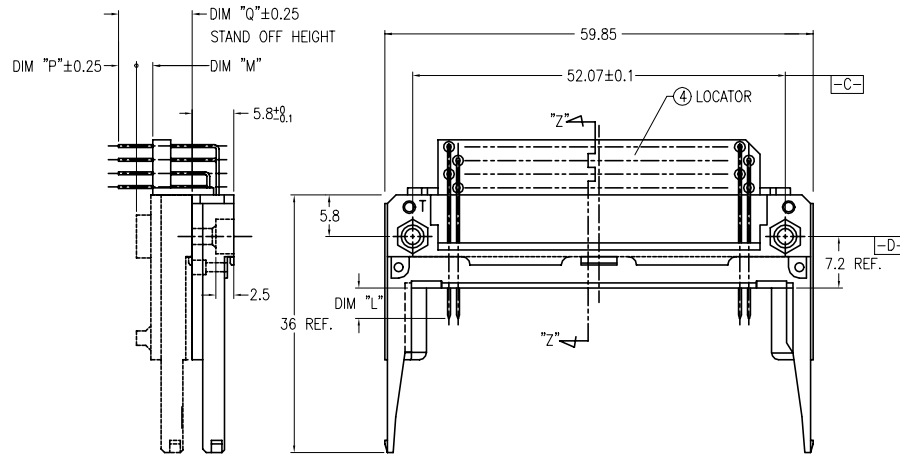
SOLDER AREA : 2.5 μ m MIN. Sn-Pb.
OR 2.5 μ m MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5 μ m MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3 $\pm$ 0.1
6. SEQUENCE PIN ASSIGNMENT

	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1.17, 34 35, 51, 68

7. GENERAL TOLERANCE : ± 0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION
12. "M" SHOWS IT IS LOW COST VERSION,IT IS OPTIONAL AND IN FIRST OF LETTER OF PART NO., SUCH AS 94898-020MLF IS LOW COST VERSION 94898-020LF IS NOT LOW COST VERSION.

[illegible]

PRODUCT NO.
94898-005
94898-005LF
94898-045
94898-045LF



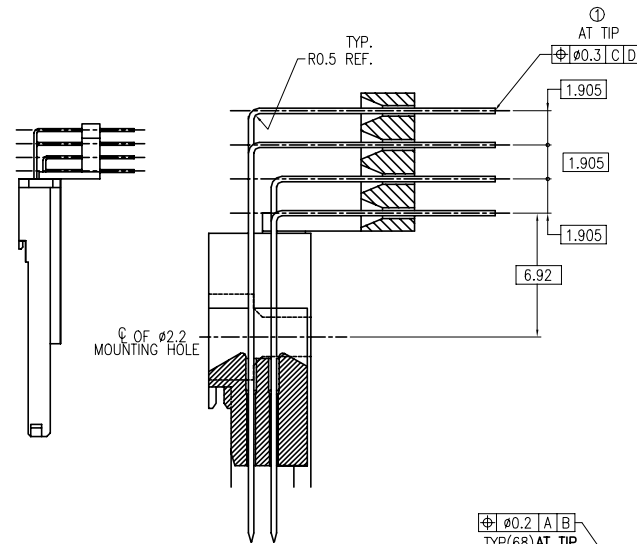
NOTES

- TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
- SEE TA-946 FOR PCB LAYOUT.
- MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
- FINISH
PIN
UNDER PLATING : 0.5µm MIN. NI.
CONTACT AREA : 0.076 µm MIN. GOLD

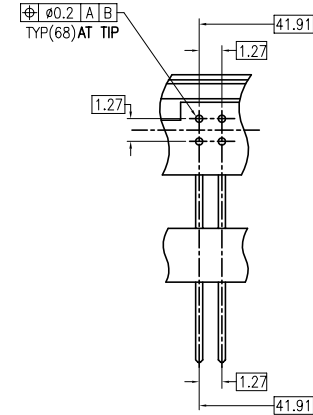
SOLDER AREA : 2.5µm MIN. Sn-Pb.
OR 2.5µm MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5µm MIN. PURE Sn.
- RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
- SEQUENCE PIN ASSIGNMENT

	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1.17.34 35.51.68

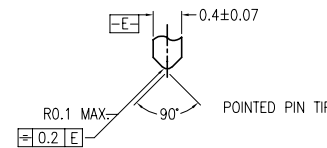
- GENERAL TOLERANCE : ±0.3
- SEE SHEET 1 REGARDING COMPONENTS.
- IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
- IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION



SECTION "Z"- "Z" (5/1)



DETAIL "Y" (5/1)

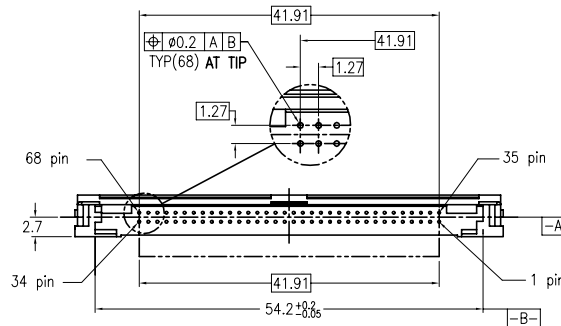
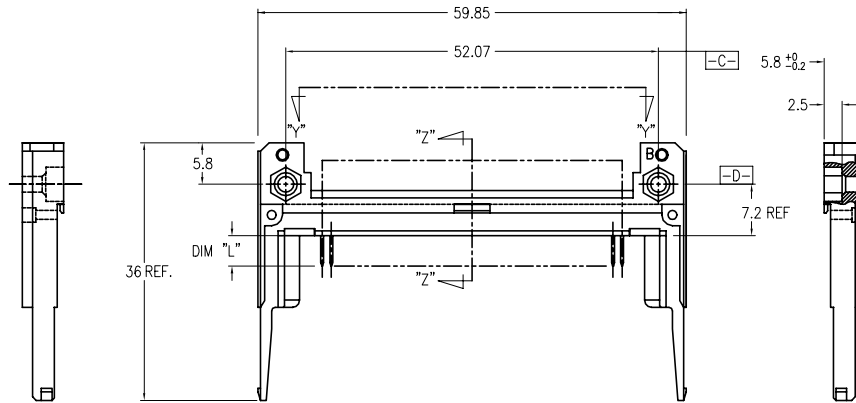


DETAIL "X" (20/1)
TYP(68)

mat'l. code		surface	tolerance	projection	product family
		ISO 1302	ISO 406 ISO 1101		PCMCIA
l	tr	ec	n	o	d
date		tolerances unless otherwise specified			title
R		angles	linear	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
		±2°	0.X±0.3 0.XX±0.13 0.XXX±0.05	scale 1:1	
		dr	M.Hasegawa	2/24/05	dwg no
		engr	M.Hasegawa	2/24/05	94898
		chr			sheet 4 of 7
		appd			size A4
sheet	revision				type CUSTOMER Drawing
index	sheet				

PRODUCT NO.
94898-500
94898-500LF
94898-500H
94898-500HLF
94898-501
94898-501LF
94898-501H
94898-501HLF
94898-502
94898-502J
94898-502LF
94898-502H
94898-502HLF

-SEE NOTE 12



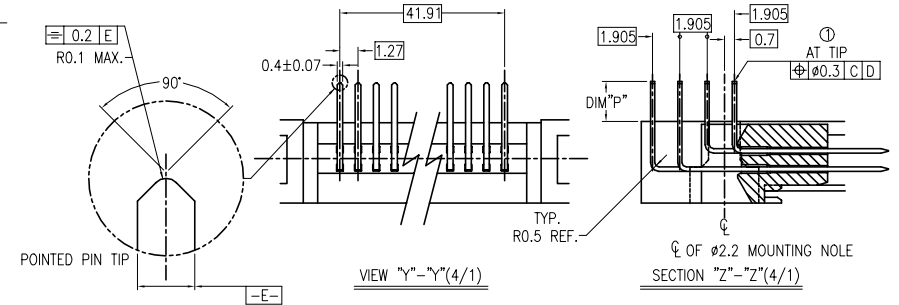
NOTES

1. TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
3. MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
4. FINISH
PIN
UNDER PLATING : 0.5μm MIN. Ni.
CONTACT AREA : 0.076 μm MIN. GOLD
SOLDER AREA : 2.5μm MIN. Sn-Pb.
OR 2.5μm MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5μm MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1

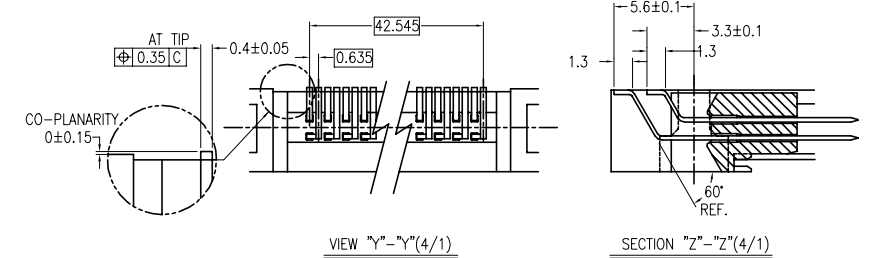
6. SEQUENCE PIN ASSIGNMENT

	DIM "L"
4.25±0.1	3.5±0.1
5.0±0.1	1.75
36.67	35.51±0.68

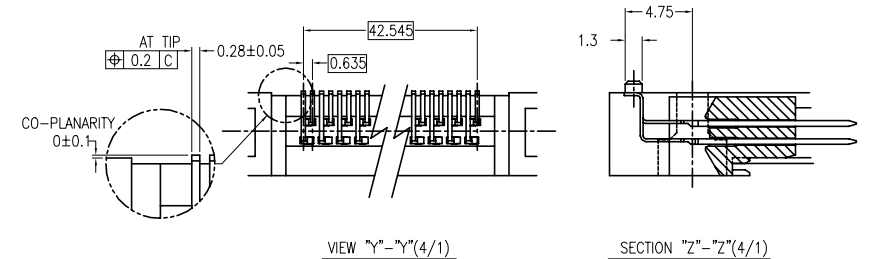
7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION
12. THE P/N 94898-502J HAS SPECIAL TRAY, IT IS 10084720-001.



R/A (94898-500X)



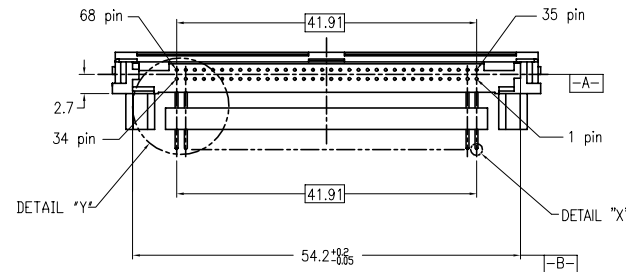
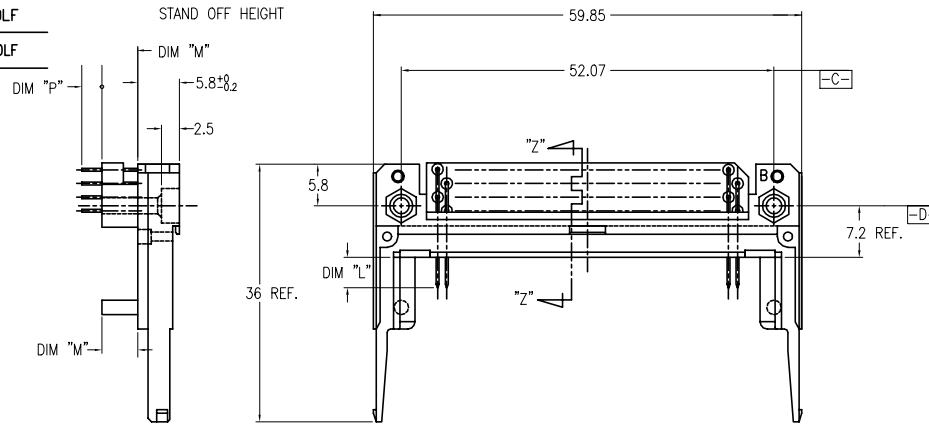
SMT STAGGERED (94898-501X)



SMT IN LINE (94898-502X)

mat'l. code				surface		tolerance		projection		product family			
				ISO 1302		ISO 406 ISO 1101				PCMCIA			
ltr		ecn no		dr		date		tolerances unless otherwise specified		title			
R										68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE			
						angles		linear		0.X±0.3			
										MM			
						±2°				0.XX±0.13			
										0.XXX±0.05			
								scale 1:1					
				dr		M.Hasegawa		2/24/05		dwg no			
				engn		M.Hasegawa		2/24/05		sheet 5 of 7		size	
				chr						94898		A4	
				appd						type CUSTOMER Drawing			
sheet		revision											
index		sheet											

PRODUCT NO.	
94898-510	94898-510LF
94898-520	94898-520LF
94898-530	94898-530LF
94898-540	94898-540LF



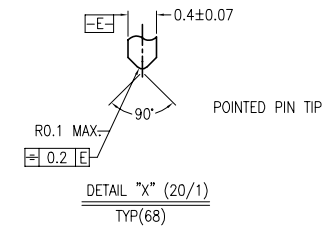
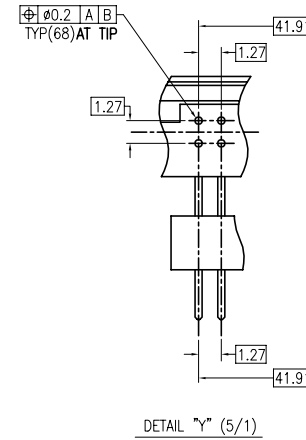
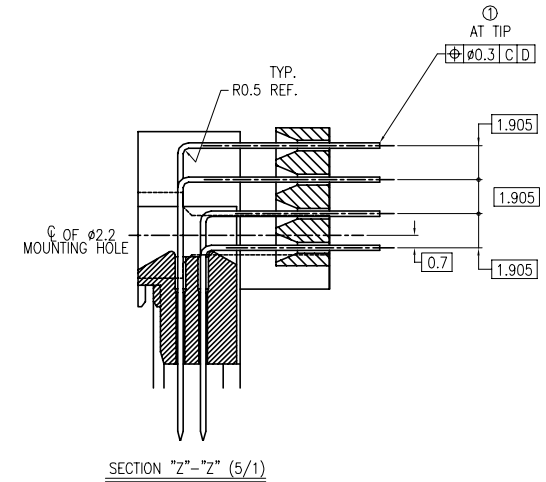
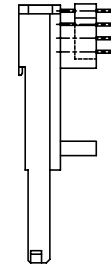
NOTES

- TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
- SEE TA-946 FOR PCB LAYOUT.
- MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
- FINISH
PIN
UNDER PLATING : 0.5µm MIN. Ni.
CONTACT AREA : 0.076 µm MIN. GOLD

SOLDER AREA : 2.5µm MIN. Sn-Pb.
OR 2.5µm MIN. PURE Sn.(FOR -XXLF)
HOLD-DOWN : 2.5µm MIN. PURE Sn.
- RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
- SEQUENCE PIN ASSIGNMENT

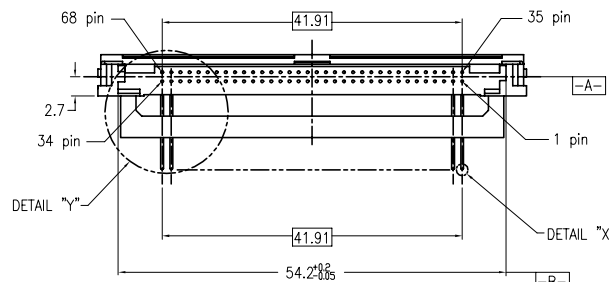
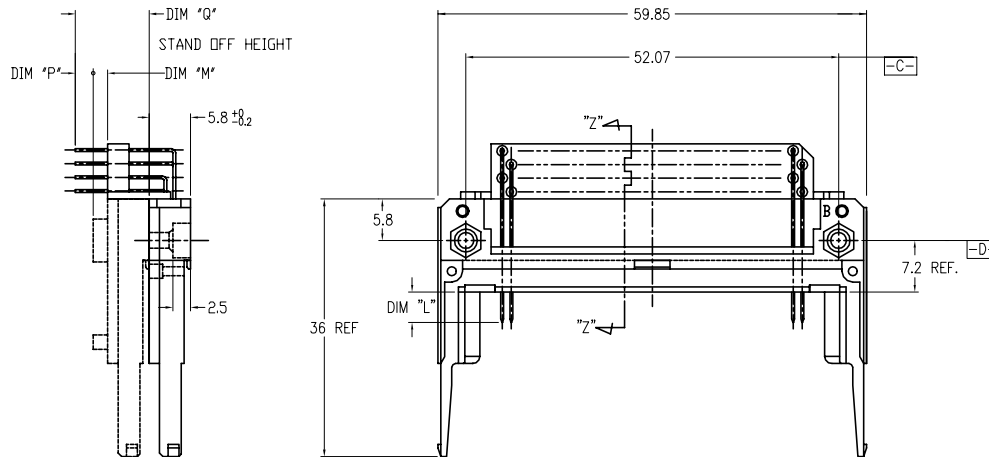
PIN No.	DIM "L"	
	4.25±0.1	3.5±0.1
OTHERS	36.67	5.0±0.1

- GENERAL TOLERANCE : ±0.3
- SEE SHEET 1 REGARDING COMPONENTS.
- IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
- IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION



mat'l. code		surface	tolerance	projection	product family
ISO 1302		ISO 406	ISO 1101		PCMCIA
l	tr	ec	n	o	d
date		tolerances unless otherwise specified			title
R		angles	linear	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
		±2°	0.X±0.3	scale 1:1	
			0.XX±0.13		
			0.XXX±0.05		
		dr	M.Hasegawa	2/24/05	dwg no
		eng	M.Hasegawa	2/24/05	94898
		chr			sheet 6 of 7
		app			size A4
sheet	revision	type CUSTOMER Drawing			
index	sheet				

PRODUCT NO.
94898-505
94898-505LF
94898-535
94898-535LF
94898-545
94898-545LF

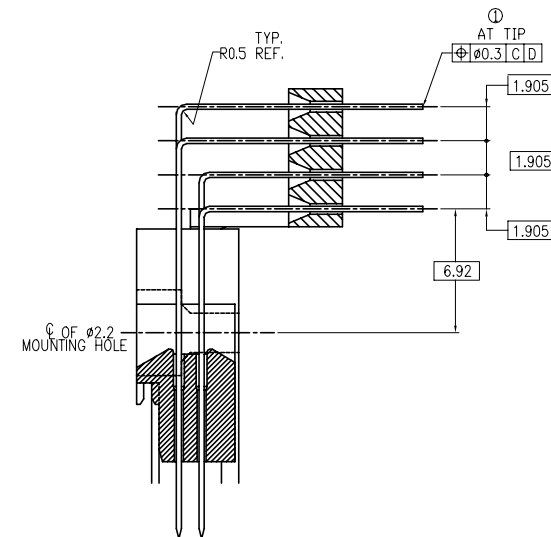
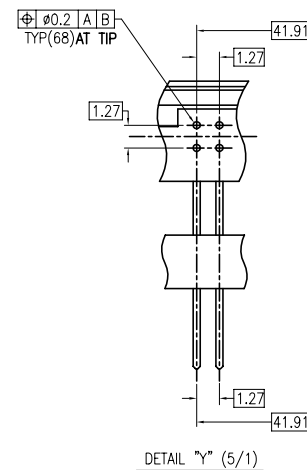
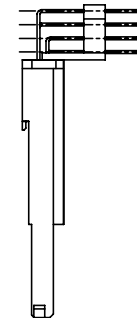


NOTES

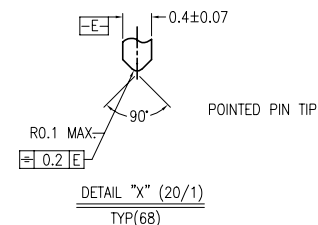
- TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
- SEE TA-946 FOR PCB LAYOUT.
- MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
- FINISH
PIN
UNDER PLATING : 0.5μm MIN. Ni.
CONTACT AREA : 0.076 μm MIN. GOLD
SOLDER AREA : 2.5μm MIN. Sn-Pb.
OR 2.5μm MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5μm MIN. PURE Sn.
- RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
- SEQUENCE PIN ASSIGNMENT

PIN No.	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36.67	117.34	35.51±0.08

- GENERAL TOLERANCE : ±0.3
- SEE SHEET 1 REGARDING COMPONENTS.
- IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCIBLED IN GS-22-008
- IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION



SECTION "Z"- "Z" (5/1)



mat'l. code				surface		tolerance		projection		product family																			
				ISO 1302		ISO 406 ISO 1101				PCMCIA																			
ltr	ec	n	o	d	r	date	tolerances unless otherwise specified													title									
R							angles		linear		0.X±0.3				68 POS EJECTOR HEADER ASSY														
							±2°				0.XX±0.13				FOR LOW VOLTAGE														
											0.XXX±0.05		scale 1:1																
						dr	M.Hasegawa		2/24/05						dwg no		sheet 7 of 7				size								
						eng	M.Hasegawa		2/24/05						94898						A4								
						chr																							
						app																							
sheet		revision																											
index		sheet																											